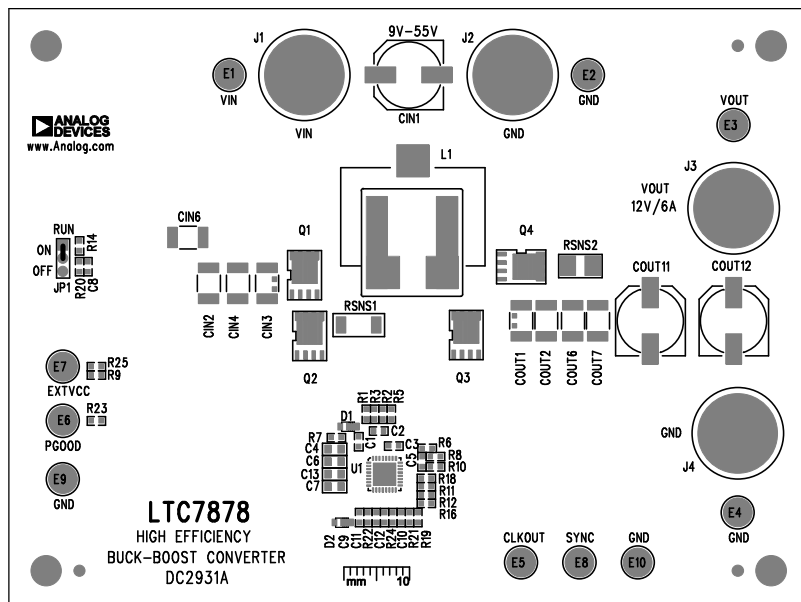


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
-	3	PRODUCTION	GORAN P.	03-30-22

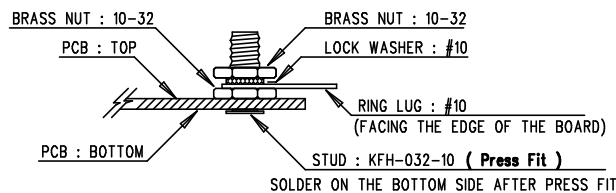
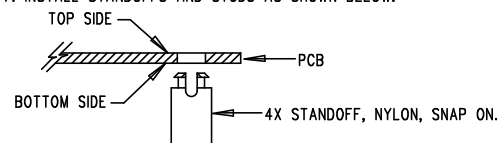


TOP SILKSCREEN

ANALOG DEVICES
DC2931A-3 DATE: 03-30-22

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL STANDOFFS AND STUDS AS SHOWN BELOW:



APPROVALS		ANALOG DEVICES		
PCB DES.	AN	TITLE: TOP ASSEMBLY DRAWING HIGH EFFICIENCY BUCK-BOOST CONVERTER		
APP ENG.	GORAN P.			
		SIZE	IC NO.	REV.
		N/A	LTC7878AUH DC2931A	3
SCALE = NONE		FILENAME: DC2931A-3.PCB		SHT 1 OF 2